

## Power line chokes

Current-compensated D core double chokes  
250 V AC, 3.3 ... 100 mH, 0.4 ... 2.2 A, +40 °C

**Series/Type:**            **B82732R/W**

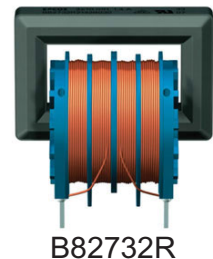
**Date:**                    December 2016

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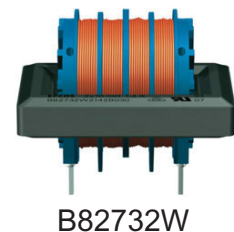
EPCOS AG is a TDK Group Company.

**Rated voltage 250 V AC**
**Rated inductance 3.3 ... 100 mH**
**Rated current 0.4 ... 2.2 A / +40 °C**
**Construction**

- Current-compensated double choke
- Closed rectangular ferrite core
- Closed plastic coil former (UL 94 V-0)<sup>1)</sup>
- Without encapsulation
- 2-section winding
- Clearance and creepage distances  $\geq 3$  mm


**Features**

- High resonance frequency due to 2-section winding
- Approx. 1% stray inductance for symmetrical interference suppression
- Low leakage due to closed core shape
- High pulse strength
- Low whirring noise
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2) and UL 1283
- UL<sup>2)</sup> and ENEC (VDE) approvals
- Recyclable owing to omission of encapsulation and glue
- RoHS-compatible


**Applications**

- Suppression of common-mode interferences
- Switch-mode power applications
- Electronic ballasts in lamps

**Terminals**

- Base material CuNi18Zn20
- Layer composition Ni, Sn
- Hot-dipped
- Pins 0.6 × 0.6 (mm)
- Lead spacing 10 × 12.5 (mm)

**Marking**

Manufacturer, rated inductance, rated current, ordering code, approval symbols, date of manufacture (WWYY)

**Delivery mode**

Blister tray in cardboard box

1) Additionally certified values:

Glow wire flammability index (GWFI to IEC 60695-2-12):	+850 °C
Glow wire ignition temperature (GWIT to IEC 60695-2-13):	+775 °C
Glow wire test (GWT to IEC 60695-2-11):	+750 °C, 2 s / 850 °C, 30 s
Comparative tracking index (CTI to IEC 60112):	175 V
Ball pressure test (BP to IEC 60695-10-2):	+125 °C

2) UL approval with 300 V AC.

**Dimensional drawings and pin configuration**

Vertical version (B82732R)



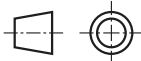
Horizontal version (B82732W)



Part tolerances to ISO 2768-cL / ISO 8015.

Size ISO 14405 (E)

All dimensions in mm





IND1276-L-E

**Technical data and measuring conditions**

Rated voltage $V_R$	250 V AC (50/60 Hz)
Test voltage $V_{test}$	1500 V AC, 2 s (line/line)
Rated temperature $T_R$	+40 °C
Rated current $I_R$	Referred to 50 Hz and rated temperature
Rated inductance $L_R$	Measured with Agilent 4284A at 0.1 mA, +20 °C, 10 kHz. Inductance is specified per winding.
Inductance tolerance	-30/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with $I_R$ , +20 °C
Stray inductance $L_{stray,typ}$	Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typ. values
DC resistance $R_{typ}$	Measured at +20 °C, typical values, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 ±3) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 11 g
Approvals	IEC / EN 60938-2, UL 1283 (E70122)

**Characteristics and ordering codes**

$I_R$ A	$L_R$ mH	$L_{stray,typ}$ μH	$R_{typ}$ mΩ	Ordering code		Approvals	
				Vertical version	Horizontal version		
0.4	100	850	3000	B82732R2401B030	B82732W2401B030	×	×
0.6	47	400	1400	B82732R2601B030	B82732W2601B030	×	×
0.7	39	330	1100	B82732R2701B030	B82732W2701B030	×	×
0.9	27	230	750	B82732R2901B030	B82732W2901B030	×	×
1.0	22	165	580	B82732R2102B030	B82732W2102B030	×	×
1.1	15	125	440	B82732R2112B030	B82732W2112B030	×	×
1.4	10	85	300	B82732R2142B030	B82732W2142B030	×	×
1.7	6.8	55	190	B82732R2172B030	B82732W2172B030	×	×
2.2	3.3	27	110	B82732R2222B030	B82732W2222B030	×	×

× = approval granted

**Impedance  $|Z|$  versus frequency  $f$**   
 measured with windings in parallel at +20 °C  
 typical values



**Current derating  $I_{op}/I_R$**   
 versus ambient temperature  $T_A$



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.  
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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